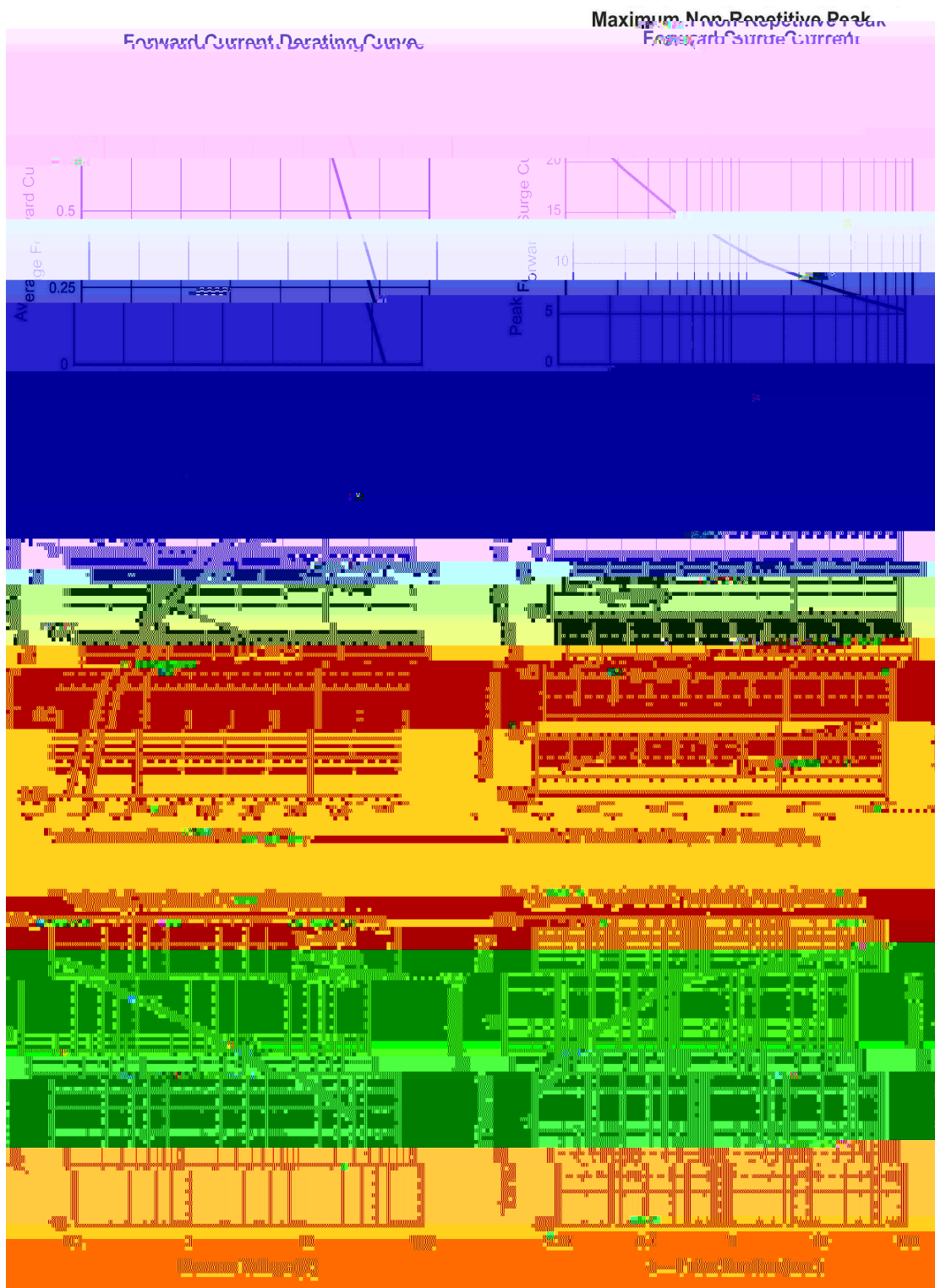
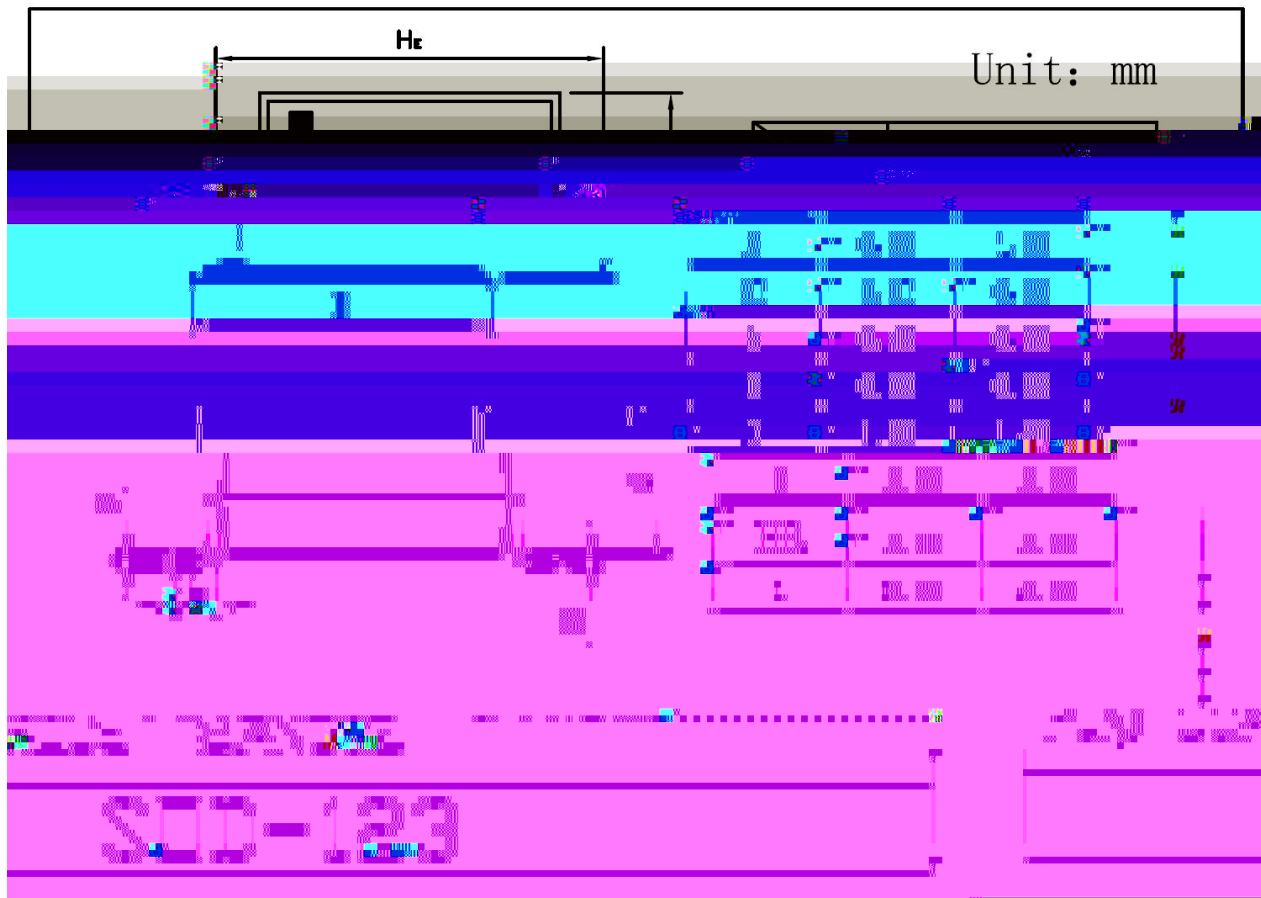




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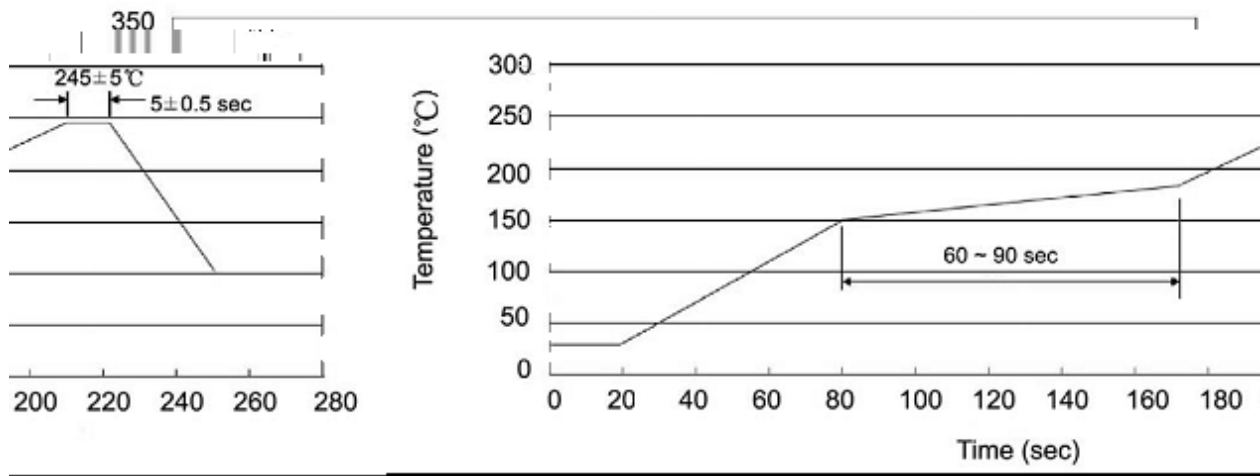






H
SJ

Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

± ± ± ±

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205